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Cho

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(54) **METHOD FOR FABRICATING CAPACITOR
IN SEMICONDUCTOR MEMORY DEVICE**

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(51) **Int. Cl.**

H01L 21/8242 (2006.01)

(52) **U.S. Cl.** **438/253**

(58) **Field of Classification Search** 438/238-244,
438/250, 253-256, 386-387, 391, 393, 396-400,
438/403-405, 424-426, 597, 600, 618, 622,
438/624, 634, 637, 658, 663, 795

See application file for complete search history.

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(57) **ABSTRACT**

Disclosed is a method for fabricating a capacitor in a
semiconductor memory device. The method includes the
steps of: sequentially forming a first insulation layer and a
first etch stop layer on a substrate; forming a plurality of
contact holes by etching the first insulation layer and the first
etch stop layer; forming a plurality of contact plugs on the
plurality of contact holes such that the contact plugs are
more projected than the first etch stop layer; sequentially
forming a second etch stop layer and a capacitor insulation
layer; forming a plurality of openings by etching the second
etch stop layer and the capacitor insulation layer to expose
the contact plugs; sequentially forming a storage node
material and a sacrificial layer; etching the storage node
material and the sacrificial layer, thereby obtaining isolated
storage node material; and removing remaining portions of
the sacrificial layer and the capacitor insulation layer.

15 Claims, 6 Drawing Sheets

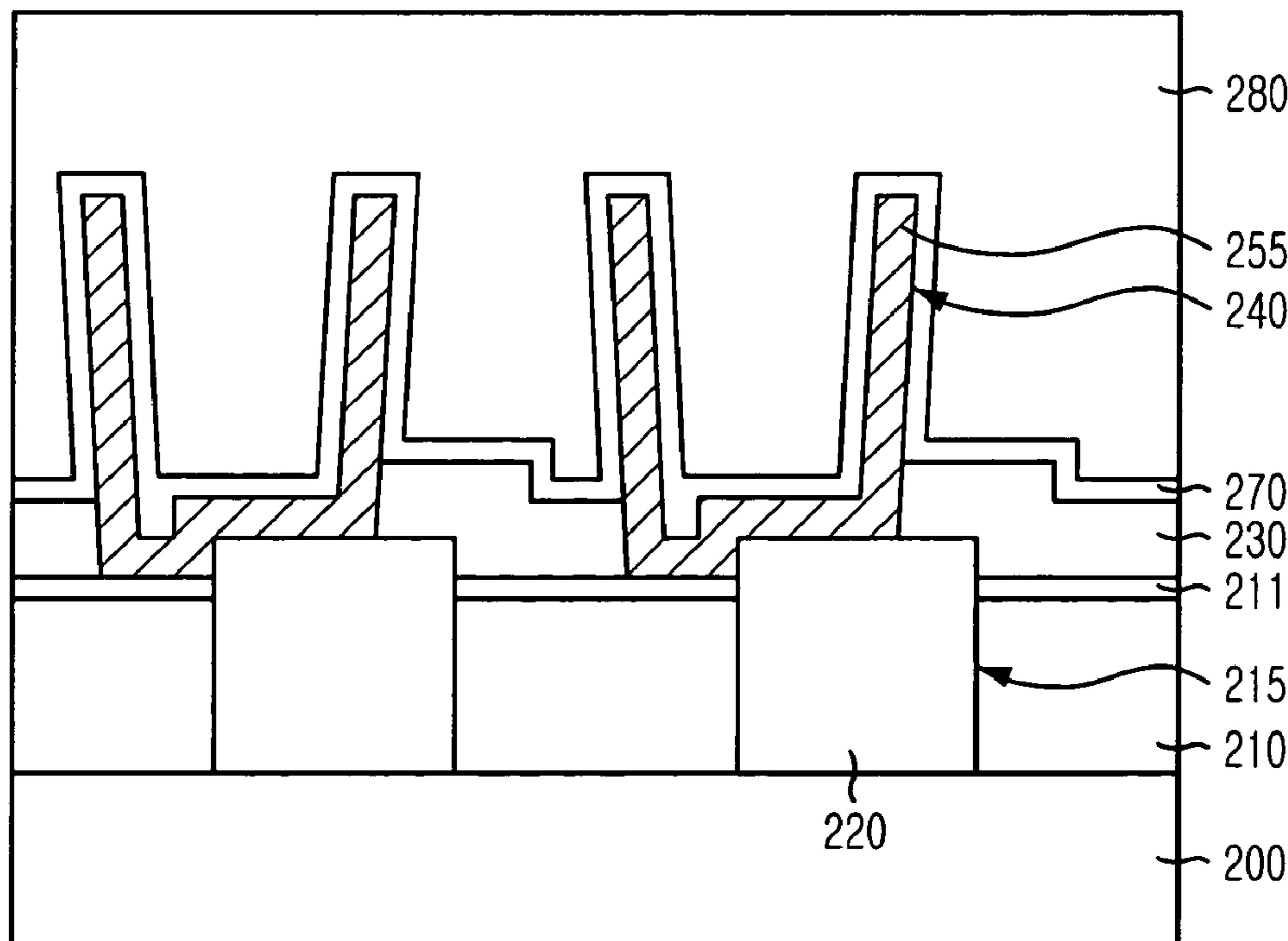


FIG. 1A
(PRIOR ART)

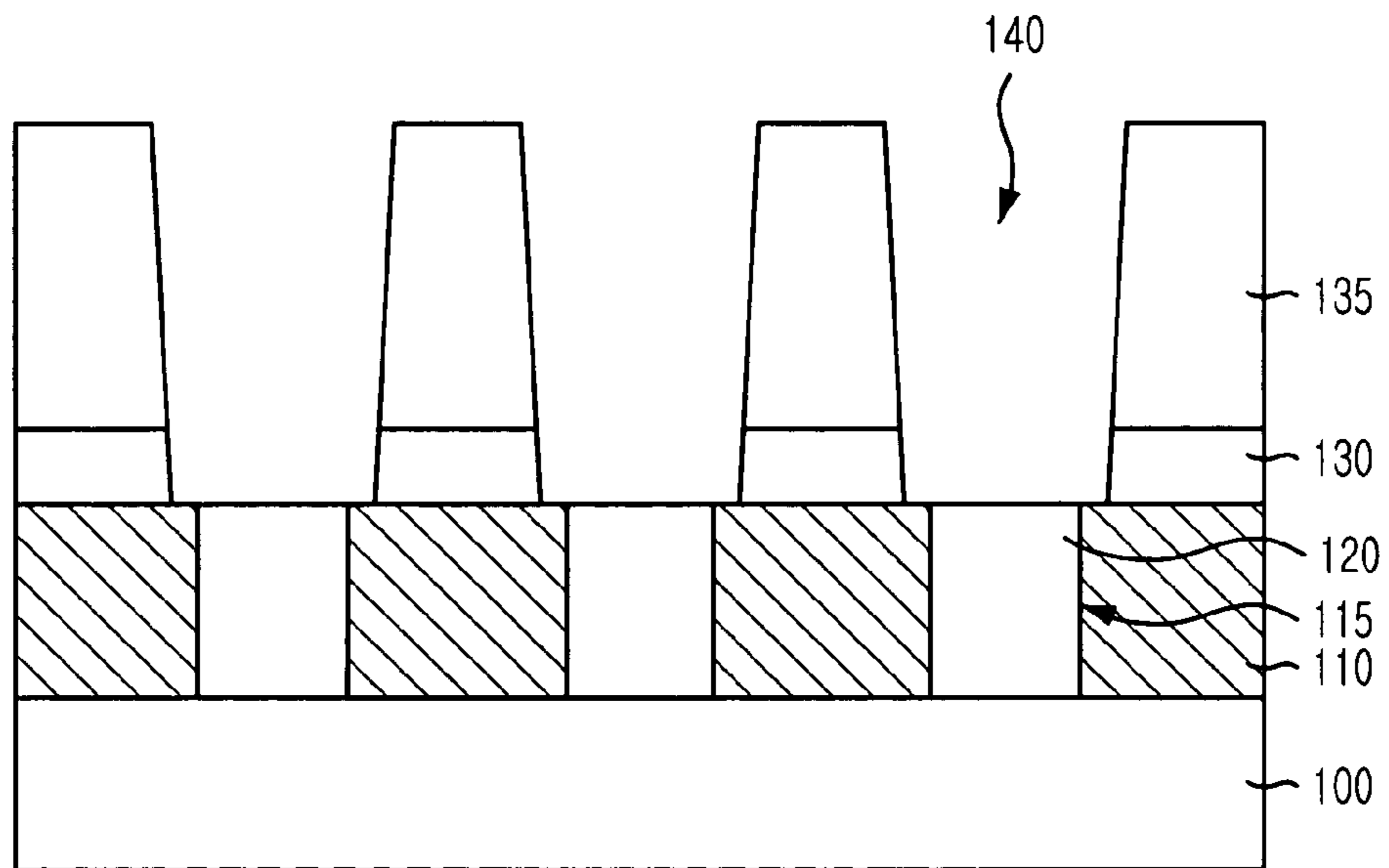


FIG. 1B
(PRIOR ART)

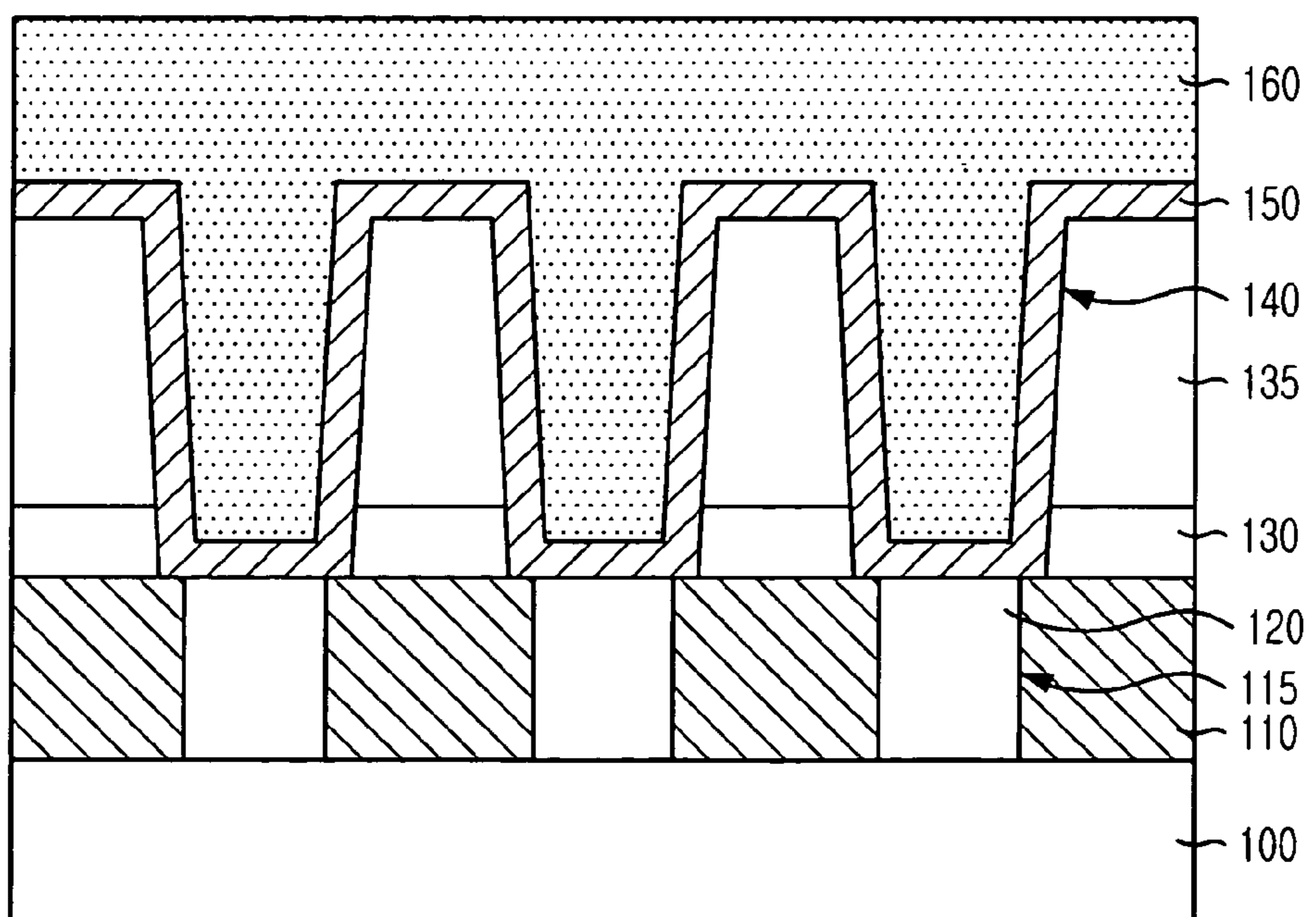


FIG. 1C
(PRIOR ART)

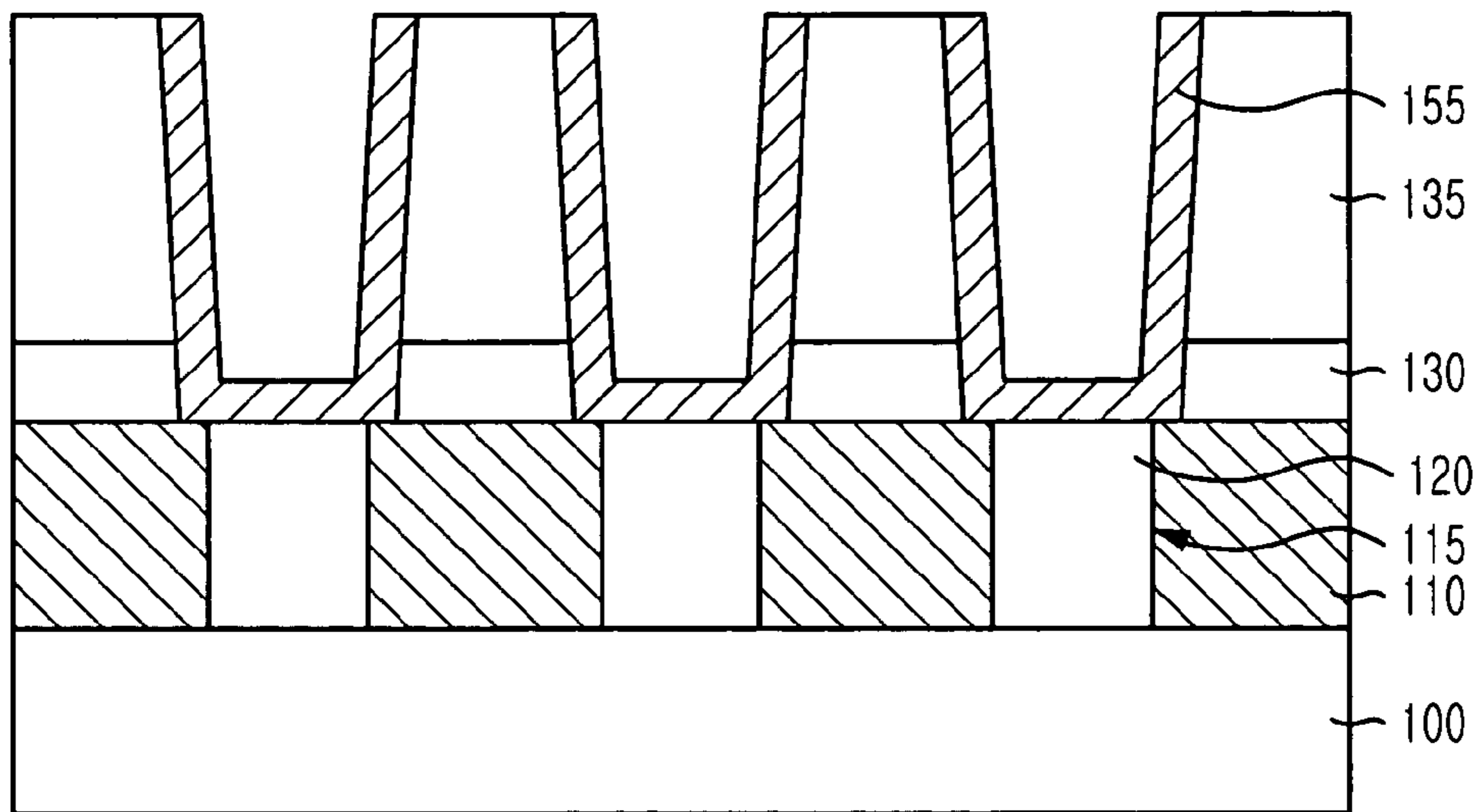


FIG. 1D
(PRIOR ART)

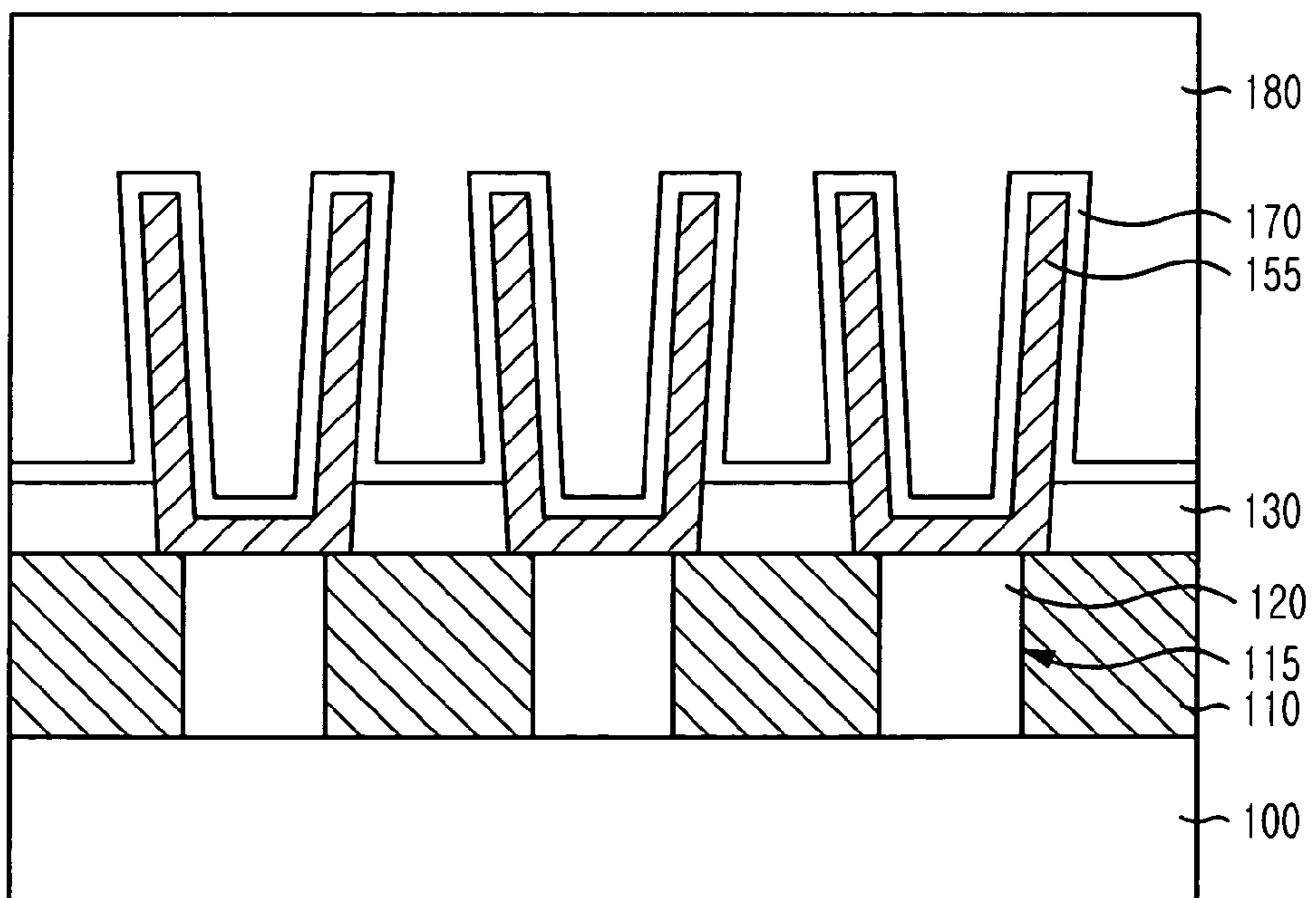


FIG. 2A

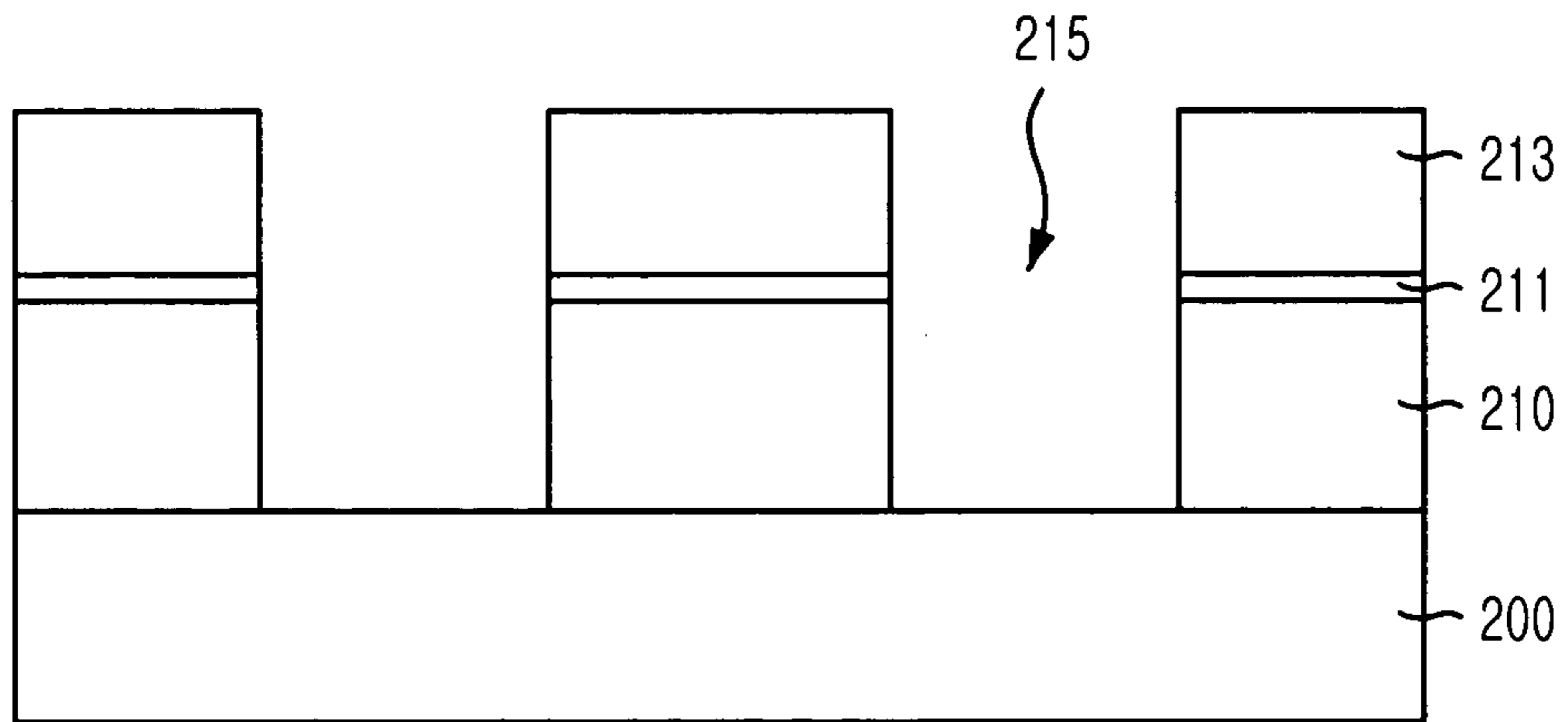


FIG. 2B

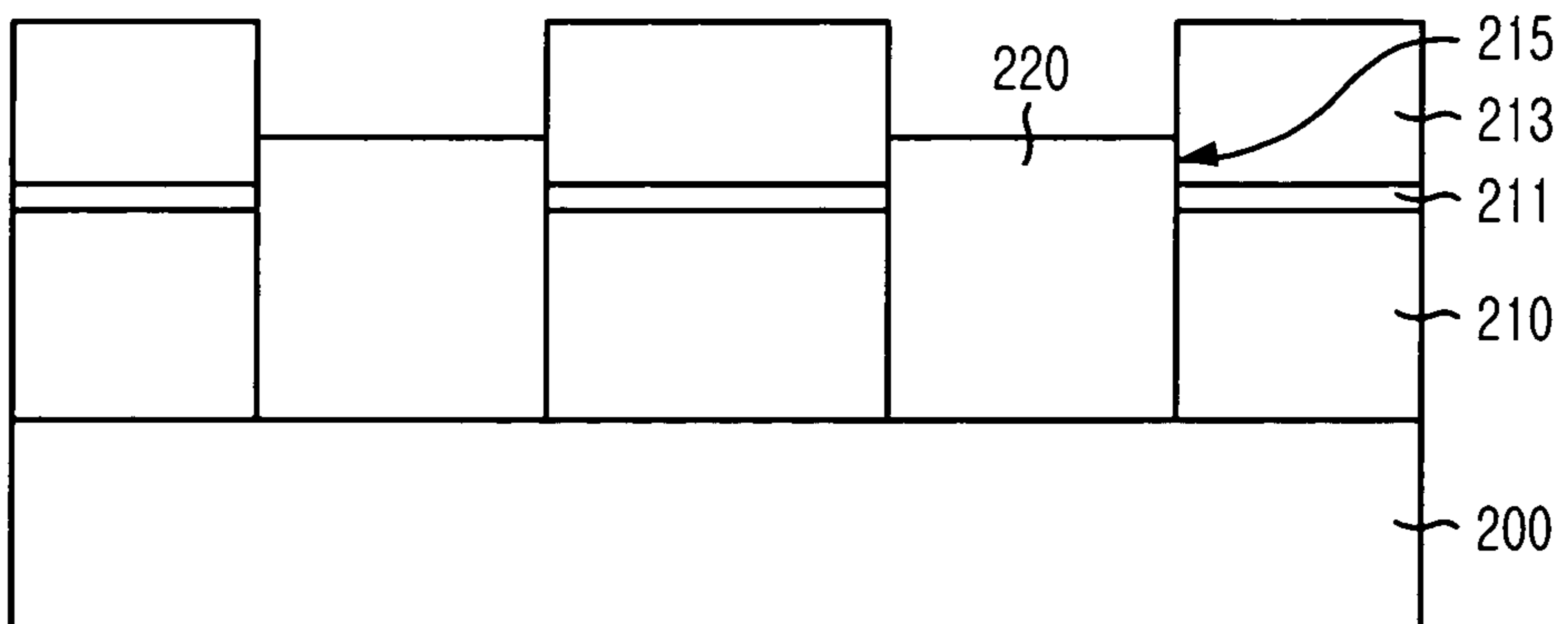


FIG. 2C

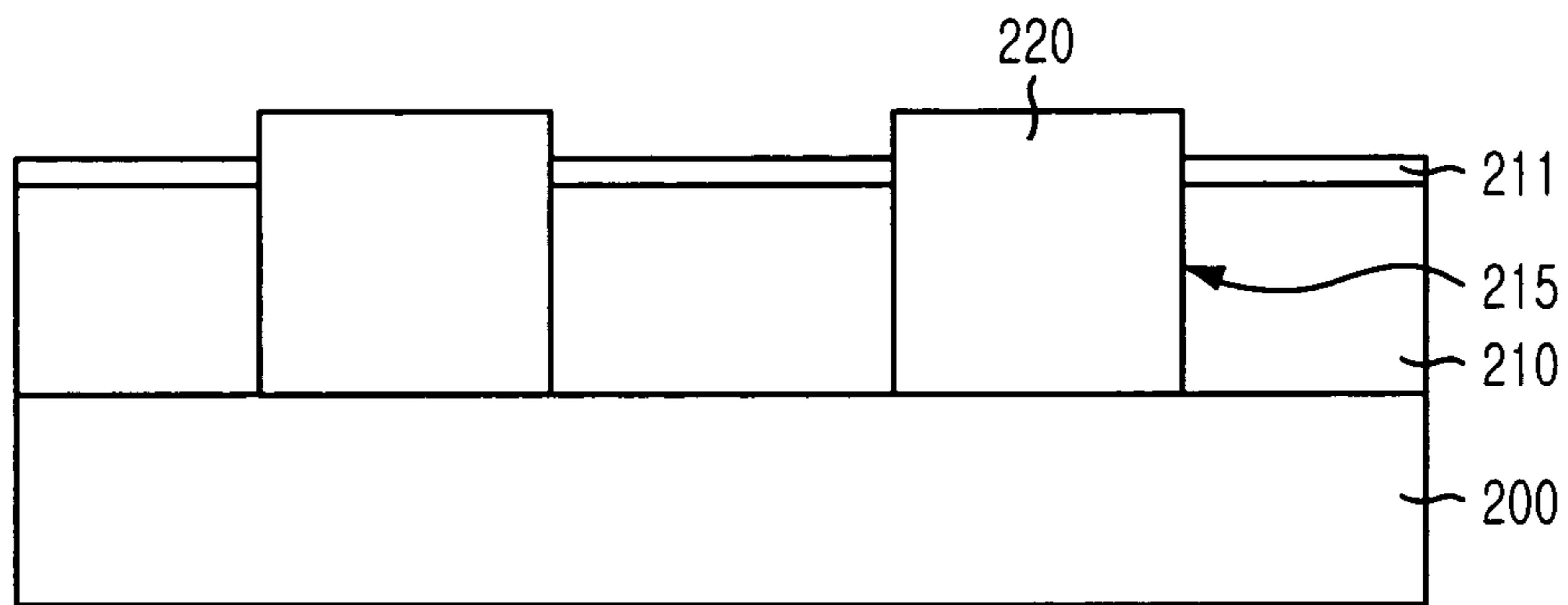


FIG. 2D

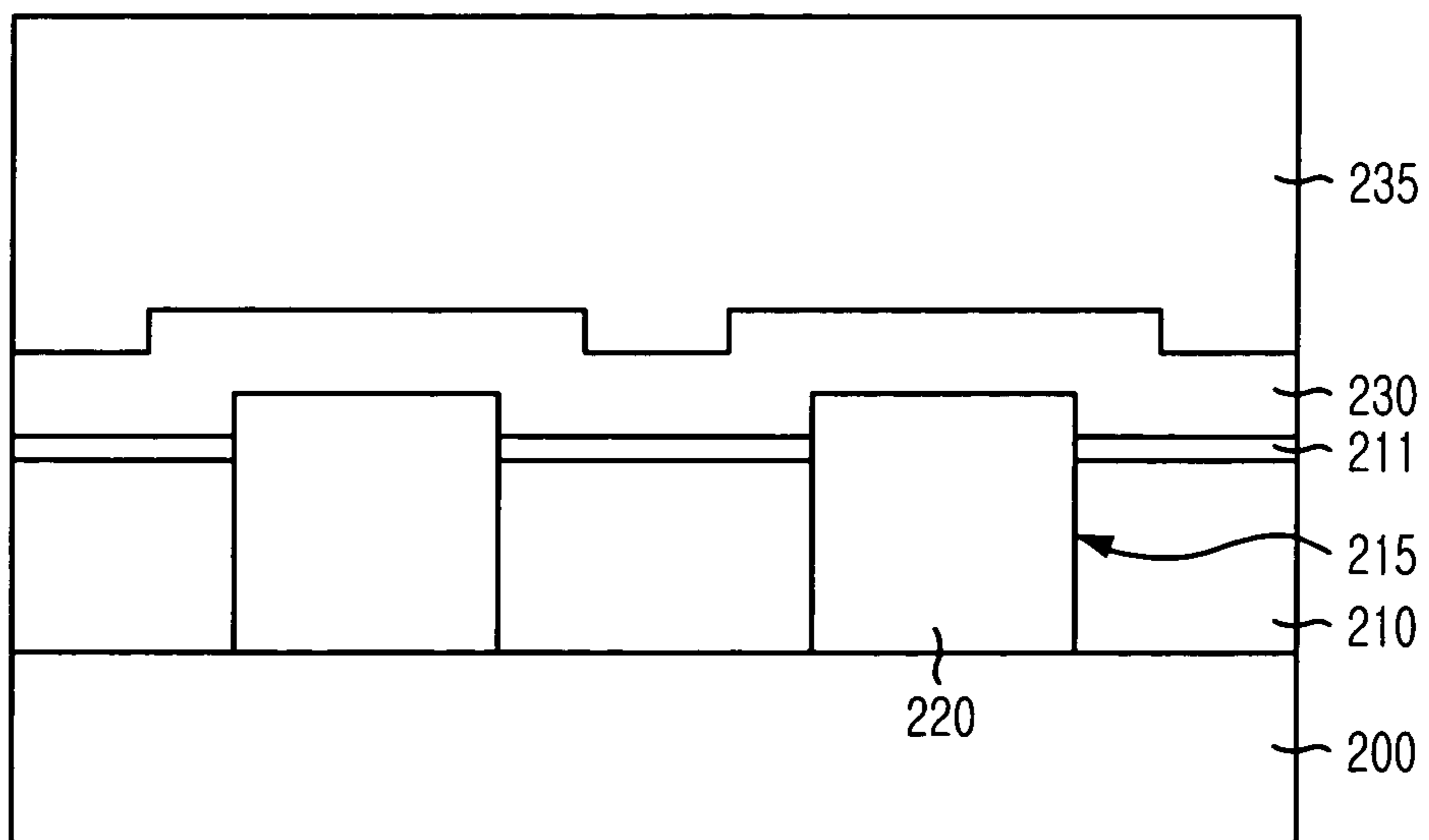


FIG. 2E

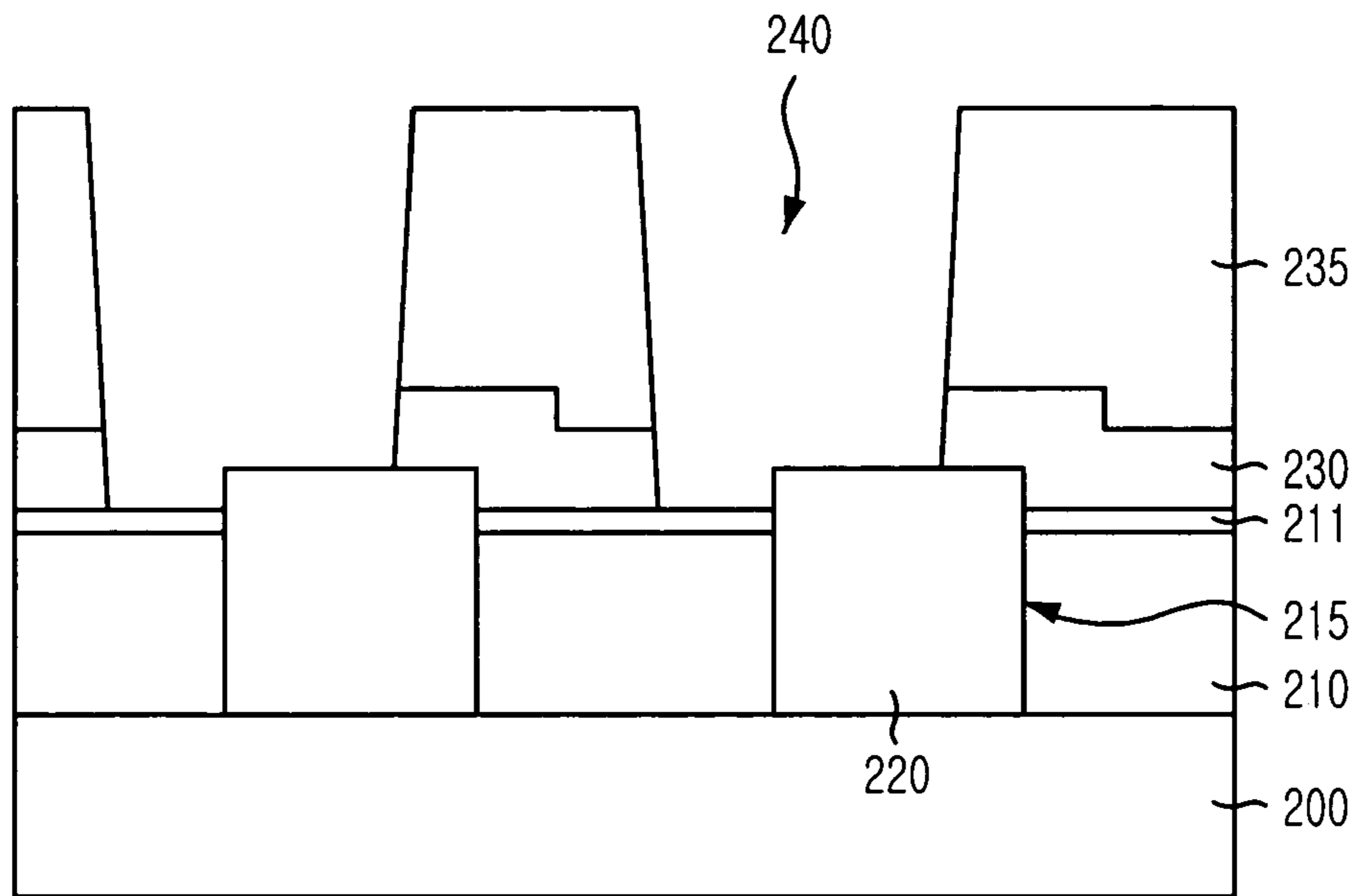


FIG. 2F

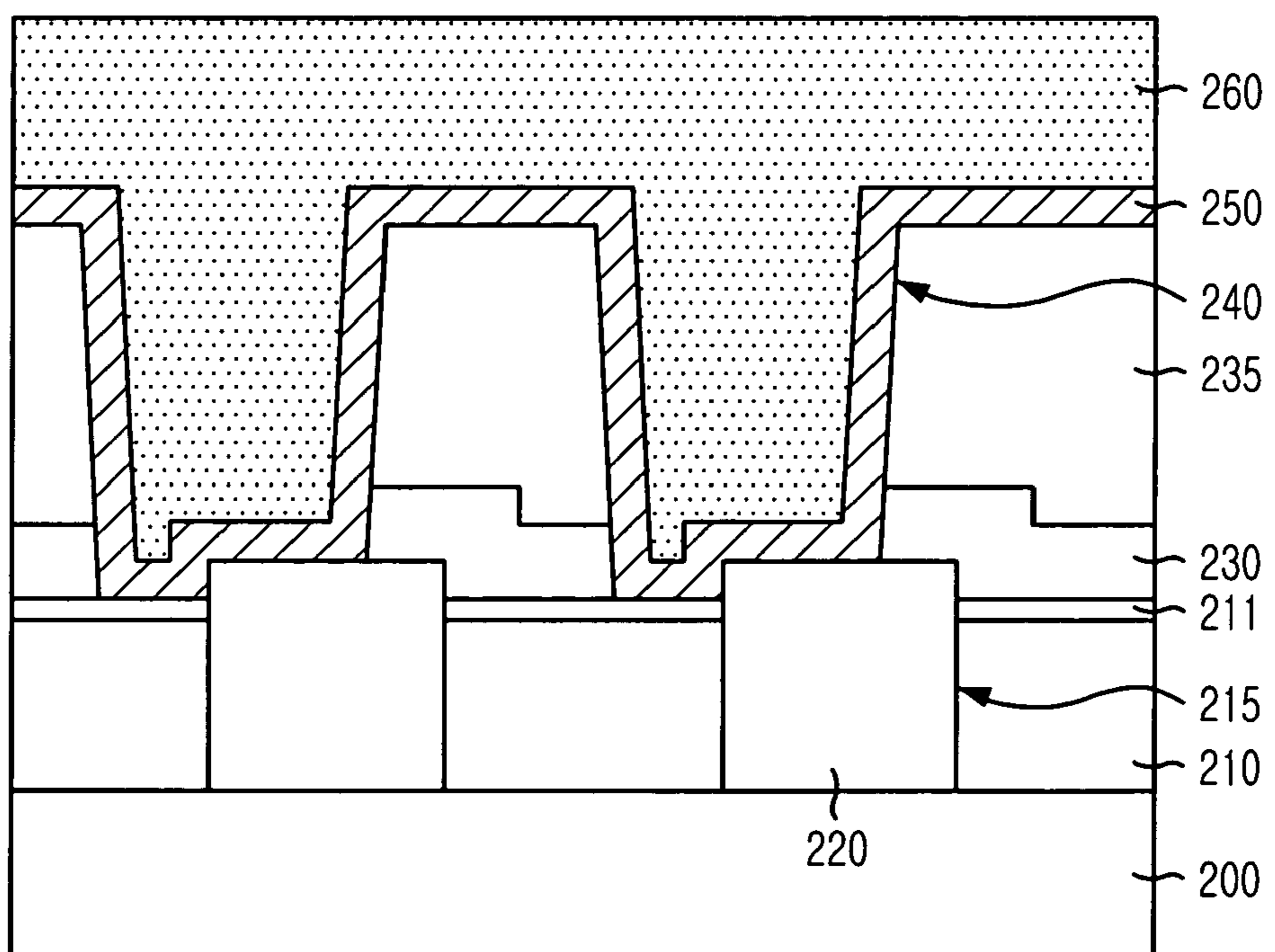


FIG. 2G

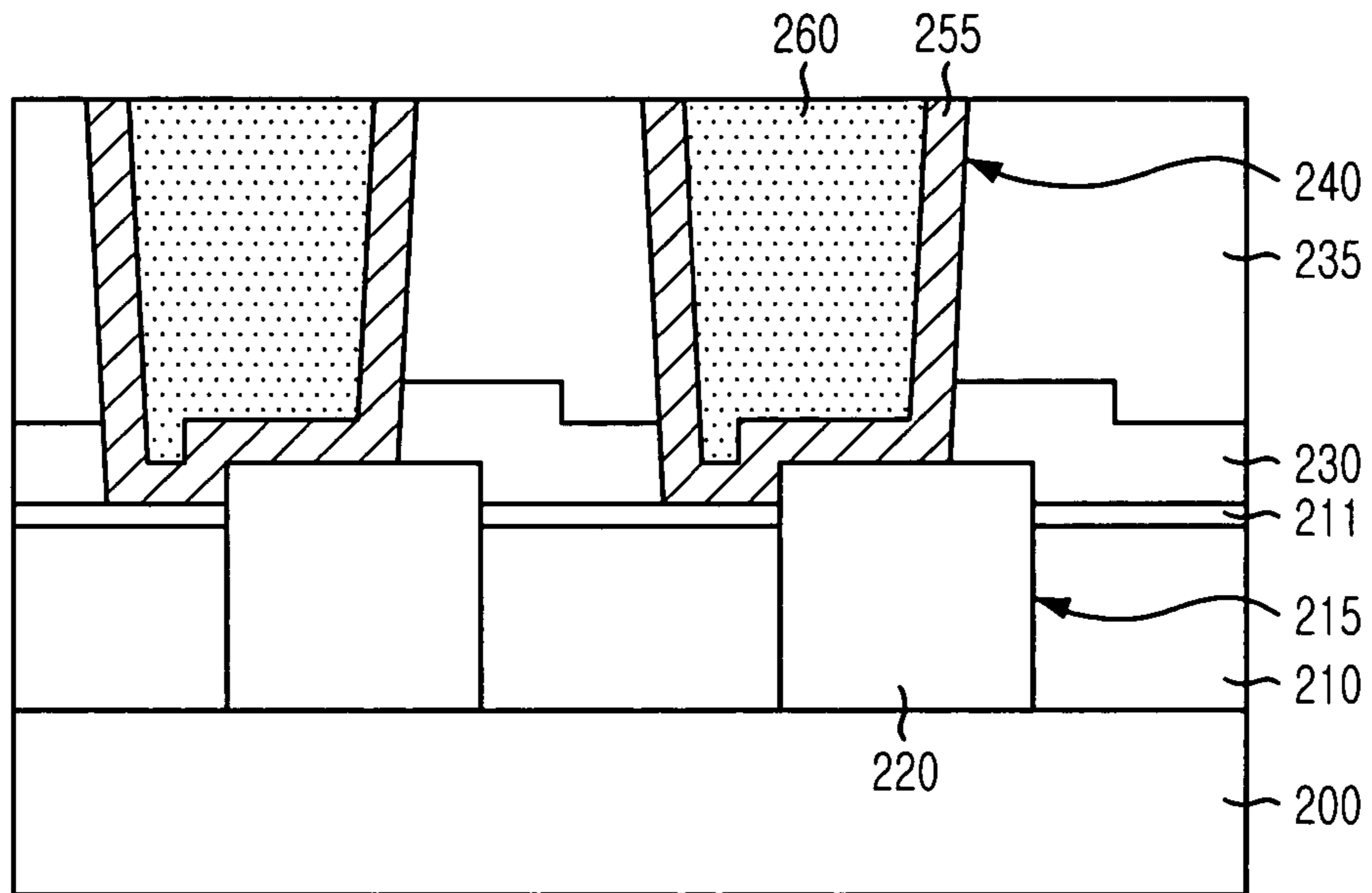
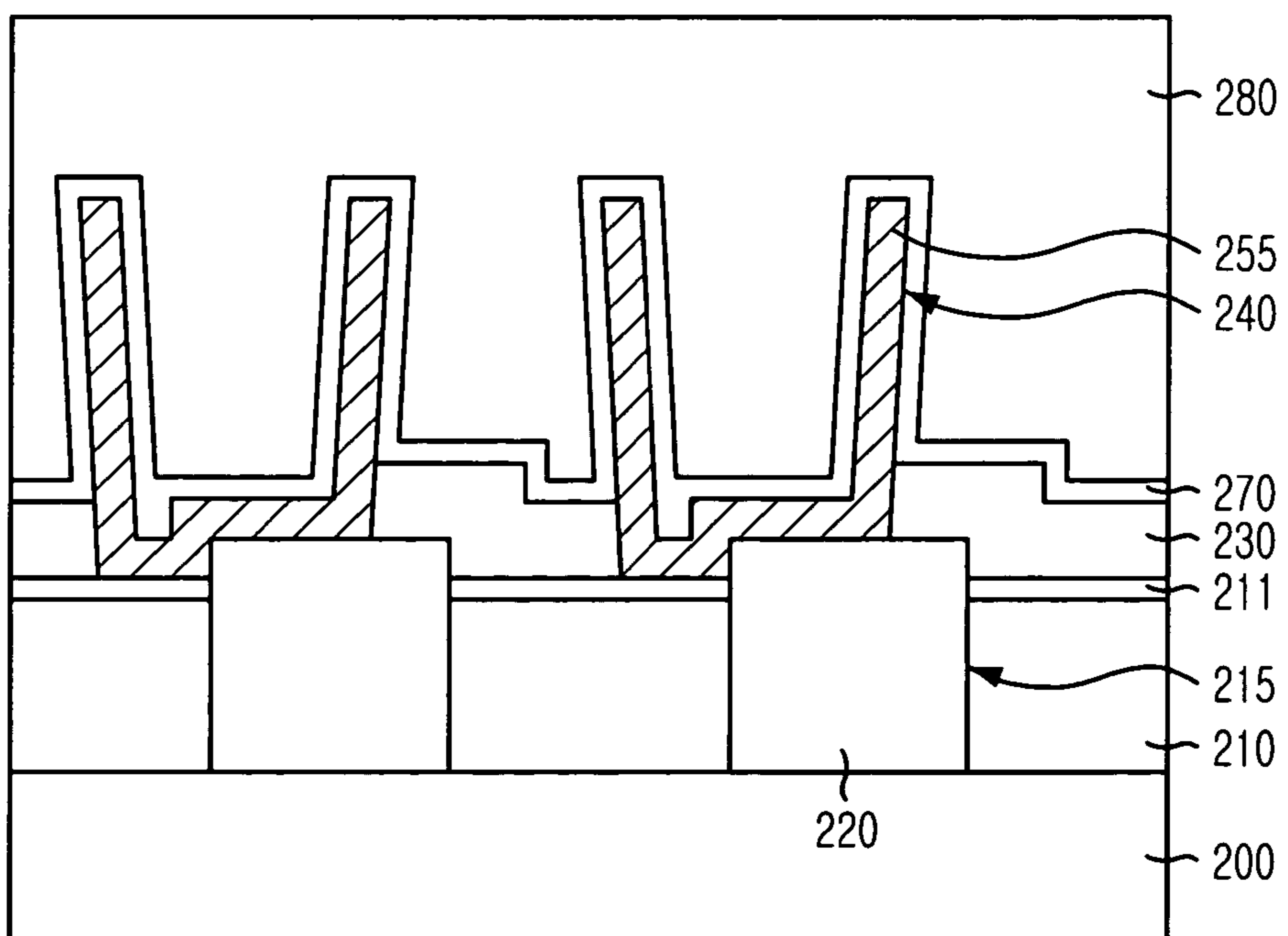


FIG. 2H



1**METHOD FOR FABRICATING CAPACITOR
IN SEMICONDUCTOR MEMORY DEVICE****CROSS-REFERENCES TO RELATED
APPLICATIONS**

Not applicable

**STATEMENT AS TO RIGHTS TO INVENTIONS
MADE UNDER FEDERALLY SPONSORED
RESEARCH OR DEVELOPMENT**

Not applicable

**REFERENCE TO A "SEQUENCE LISTING," A
TABLE, OR A COMPUTER PROGRAM LISTING
APPENDIX SUBMITTED ON A COMPACT
DISK**

Not applicable

BACKGROUND OF THE INVENTION**1. Field of the Invention**

The present invention relates to a method for fabricating a capacitor in a semiconductor memory device; and more particularly, to a method for fabricating a cylinder type capacitor capable of preventing a damage in a bottom structure disposed beneath the capacitor by forming a plurality of storage node contact plugs in a well type.

2. Description of Related Arts

As for a capacitor of a semiconductor memory device, both an outer wall and an inner wall of a cylinder type lower electrode function as electrodes. Accordingly, it is possible to improve a capacitance by increasing a surface area of the capacitor.

FIGS. 1A to 1D are cross-sectional views illustrating a conventional method for fabricating a capacitor in a semiconductor memory device.

Referring to FIG. 1A, an inter-layer insulation layer **110** is formed on a silicon substrate **100**, and a plurality of storage node contact plugs **120** are formed on corresponding storage node contacts **115** formed by etching the inter-layer insulation layers **110**. An etch stop layer **130** and a capacitor insulation layer **135** are formed on the above resulting substrate structure and then, predetermined portions of the etch stop layer **130** and the capacitor insulation layer **135** corresponding to the plurality of contact plugs **120** are etched, thereby forming a plurality of openings **140** for storage nodes. Herein, the capacitor insulation layer **135** is an oxide-based layer.

Referring to FIG. 1B, a storage node material **150** such as titanium nitride (TiN) and a sacrificial layer **160** are sequentially deposited on openings **140**.

Referring to FIG. 1C, the storage node material **150** and the sacrificial layer **160** are subjected to a plasma blanket etch-back process and as a result, a plurality of storage nodes **155** are isolated. After a process for isolating the plurality of storage nodes **155**, the sacrificial layer **160** is removed.

Referring to FIG. 1D, the plurality of cylinder type storage nodes **155** are formed by removing the capacitor insulation layer **135** with use of a chemical such as hydrofluoric acid (HF) or buffered oxide etchant (BOE). Subsequently, a dielectric layer **170** and a plate node **180** are formed.

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However, in the course of forming the capacitor, there is a misalignment between the plurality of storage nodes which are lower electrodes and the plurality of storage node contact plugs. Accordingly, when the lower electrodes are formed by using a metal such as TiN and then, are dipped into the chemical such as HF or BOE to remove the capacitor insulation layer under a state that the misalignment is generated between the plurality of storage nodes and the plurality of storage node contact plugs, the TiN layer which is the lower electrode cannot properly serve a role as a blocking layer.

This result is because there generates a crack in the TiN layer during the step of controlling contents of titanium chloride (TiCl₂) within the TiN layer.

Accordingly, during the dipping process for removing the capacitor insulation layer, a chemical path is created at the crack of the TiN layer and thus, the chemical such as HF or BOE is penetrated through the chemical path created by the misalignment between the plurality of storage nodes and the plurality of storage nodes contact plugs. Accordingly, because of the penetrated chemical, the plurality of storage node contact plugs or the oxide layer which is the inter-layer insulation layer is susceptibly damaged, thereby inducing various defects such as a single and dual bit failure, and a direct current (DC) failure, which further causes decrease in yields of semiconductor devices and a poor operation

BRIEF SUMMARY OF THE INVENTION

It is, therefore, an object of the present invention to provide a method for fabricating a capacitor in a semiconductor memory device capable of preventing a damage in a bottom structure disposed beneath the capacitor by forming a plurality of storage node contact plugs in a well type.

In accordance with one aspect of the present invention, there is provided a method for fabricating a capacitor in a semiconductor memory device, including the steps of: sequentially forming a first insulation layer and a first etch stop layer on a substrate; forming a plurality of contact holes by etching the first insulation layer and the first etch stop layer; forming a plurality of contact plugs on the plurality of contact holes such that the contact plugs are more projected than the first etch stop layer; sequentially forming a second etch stop layer and a capacitor insulation layer; forming a plurality of openings by etching the second etch stop layer and the capacitor insulation layer to expose the contact plugs; sequentially forming a storage node material and a sacrificial layer; etching the storage node material and the sacrificial layer, thereby obtaining isolated storage node material; and removing remaining portions of the sacrificial layer and the capacitor insulation layer.

BRIEF DESCRIPTION OF THE DRAWINGS

The above and other objects and features of the present invention will become better understood with respect to the following description of the preferred embodiments given in conjunction with the accompanying drawings, in which:

FIGS. 1A to 1D are cross-sectional views illustrating a conventional method for fabricating a capacitor in a semiconductor memory device; and

FIGS. 2A to 2H are cross-sectional views illustrating a method for fabricating a capacitor in a semiconductor memory device in accordance with the present invention.

DETAILED DESCRIPTION OF THE
INVENTION

Hereinafter, detailed descriptions on a preferred embodiment of the present invention will be provided with reference to the accompanying drawings.

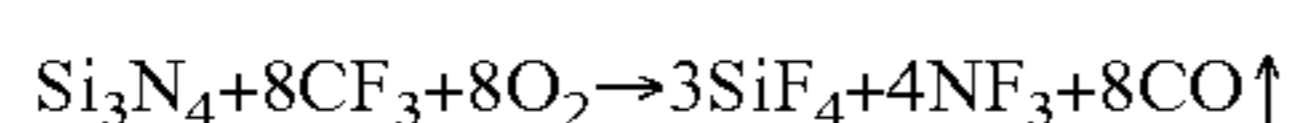
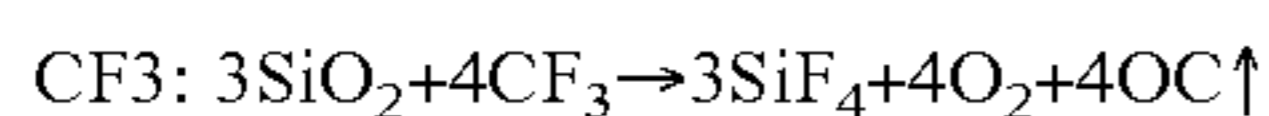
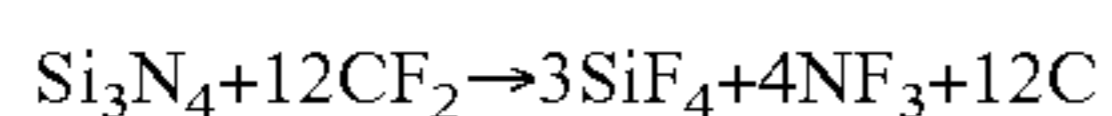
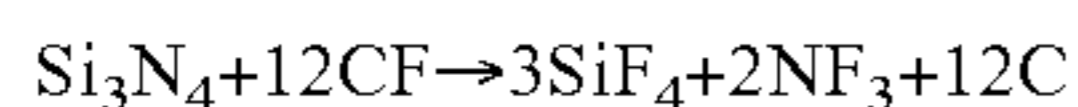
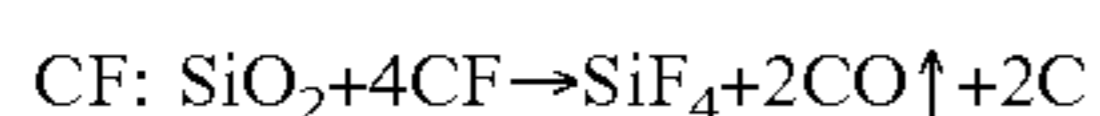
FIGS. 2A to 2H are cross-sectional views illustrating a method for fabricating a capacitor in a semiconductor memory device in accordance with the present invention.

Referring to FIG. 2A, an inter-layer insulation layer **210** is deposited on a silicon substrate **200** and then, a first etch stop layer **211** and an insulation layer **213** for forming a plurality of storage node contact holes **215** are sequentially formed thereon. The first etch stop layer **211** is made of nitride and is deposited in a thickness ranging from approximately 100 Å to approximately 300 Å. The insulation layer **213** is made of a material having a high etch ratio that allows the insulation layer **213** to be easily removed by using a chemical. Oxide is one example of such material. Also, the insulation layer **213** is deposited in a thickness ranging from approximately 500 Å to approximately 1,000 Å.

Subsequently, although not illustrated, a photo-sensitive layer is deposited on the insulation layer **213** and then, the photo-sensitive layer is patterned such that the photo-sensitive layer placed in which the plurality of storage node contact holes **215** will be formed is removed, thereby exposing the insulation layer **213**. The exposed insulation layer **213**, the first etch stop layer **211** and the inter-layer insulation layer **210** are etched by using the photo-sensitive layer, thereby forming the aforementioned plurality of storage node contact holes **215**.

At this time, a multi layer formed by stacking the inter-layer insulation layer **210**, the first etch stop layer **211** and the insulation layer **213** are etched in a ratio of approximately 2 to 3 of C_xHF_x to 1 of C_xF_x which are high density plasmas of a magnetically enhanced reactive ion etching (MERIE) type. That is, the multi-layer is etched by inducing a lot of CH_x radicals by using a CH_xF_x plasma, e.g., a CHF_3 plasma and a CH_2F_2 plasma, along with use of CH_4 as a main gas. During etching the multi-layer, one of plasma etchers selected from a group of an in-plane switching (IPS), an inductively coupled plasma (ICP), a transformer coupled plasma (TCP) and an electron cyclotron resonance (ECR) plasma etchers is used.

Reaction mechanisms of C_xF_x gas used for etching the multi-layer are provided below. Herein, the first provided reaction of each C_xF_x gas is a reaction when each C_xF_x gas reacts with an oxide layer and the second provided reaction of each C_xF_x gas is a reaction when each C_xF_x gas reacts with a nitride layer.



Referring to FIG. 2B, a polysilicon layer for use in a storage node contact plug is formed on the above obtained substrate structure and then, one of an etch-back process and a chemical mechanical polishing (CMP) process used for a typical plug isolation process is performed, thereby forming

a plurality of storage node contact plugs **220** within the plurality of storage node contact holes **215**.

At this time, the etch back process is performed by mixing hydrogen bromide (HBr) and chlorine (Cl_2) under a state of providing a source voltage equal to or greater than approximately 300 W and a bias voltage equal to or less than approximately 100 W at a pressure equal to or less than approximately 10 mT by using a typical TCP type plasma source. Also, the etch-back process continues until the storage node contact plugs **220** have thicknesses from the first etch stop layer **211** in a range from approximately 300 Å to approximately 500 Å.

At this time, although not shown, a barrier layer such as TiSi2 can be formed in order to increase adhesiveness between the plurality of storage node contact plugs **220** made of polysilicon and lower electrodes made of TiN which will be formed in a subsequent process.

Referring to FIG. 2C, the insulation layer **213** is removed by using a wet etching process with use of one of hydrogen fluoride acid (HF) and buffered oxide etchant (BOE), so that the plurality of storage node contact plugs **220** are formed in well type.

Referring to FIG. 2D, a second etch stop layer **230** for forming a storage node is formed on the above substrate structure and a capacitor insulation layer **235** made of oxide is deposited thereon. The second etch stop layer **230** is formed by depositing a nitride layer. In accordance with the present invention, the plurality of storage node contact plugs **220** are formed to be more projected than the first etch stop layer **211** and thus, the second etch stop layer **230** is also formed to have a difference in height. Accordingly, the first etch stop layer **211** formed on lateral sides of the plurality of storage node contact plugs **220** and the second etch stop layer **230** are margins for misalignment generated during a subsequent process for forming a plurality of storage nodes.

Referring to FIG. 2E, the capacitor insulation layer **235** and the second etch stop layer **230** are etched, thereby forming a plurality of openings **240** for the storage nodes.

At this time, as shown in FIG. 2E, even though a misalignment is happened, a contact area between each two of the storage node contact plugs increases because not only upper portions of the plurality of storage node contact plugs **220** and the first etch stop layer **211** made of nitride but also lateral portions of the storage node contact plugs **220** are exposed by the openings **240**.

Referring to FIG. 2F, a storage node material **250** such as TiN is deposited and then, a sacrificial layer **260** is deposited thereon.

Referring to FIG. 2G, an etch back process or a CMP process is applied to the storage node electrode material **250** and the sacrificial layer **260** to thereby obtain isolated storage nodes **255**.

Referring to FIG. 2H, the sacrificial layer **260** is removed and then, the capacitor insulation layer **235** is removed by performing a wet etching process using one of HF and BOE, thereby forming the complete storage nodes **255**, i.e., lower electrodes. At this time, even though the misalignment is generated between each two of the storage nodes **255** and the storage node contact plugs **220**, since the well-type storage node contact plugs **220** allow the first and the second etch stop layers **211** and **230** to be disposed on each lateral side of the plurality of storage node contact plugs **220**, the storage nodes **255** are contacted with not only upper portions but also lateral portions of the plurality of contact plugs **220** and surrounded by the first and the second etch stop layers **211** and **230** at a region in which the misalignment is generated.

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Accordingly, during the wet etching process for removing the capacitor insulation layer **235**, diffusion of the wet chemical through cracks formed in the lower electrodes **255**, i.e., the TiN layer, is intercepted, and as a result, it is possible to prevent a bottom structure disposed beneath the lower electrodes **255** from being damaged. Because of the blocked penetration of the wet chemical, it is further possible to prevent generation of defects such as a single and dual bit failure and a direct current (DC) failure.

The method for fabricating a capacitor in accordance with the present invention forms a plurality of storage node plugs in a well type and etch stop layer made of nitride layers on lateral sides of the plurality of contact plugs in order to protect a bottom structure disposed beneath storage nodes from damages usually caused by a penetrated wet chemical in the course of forming the storage nodes. Accordingly, the present invention improves a property of a semiconductor device and increases yields of semiconductor devices.

The present application contains subject matter related to the Korean patent application No. KR 2004-0049857, filed in the Korean Patent Office on Jun. 30, 2004, the entire contents of which being incorporated herein by reference.

While the present invention has been described with respect to certain preferred embodiments, it will be apparent to those skilled in the art that various changes and modifications may be made without departing from the spirit and scope of the invention as defined in the following claims.

What is claimed is:

1. A method for fabricating a capacitor in a semiconductor memory device, comprising the steps of:

- forming a first insulation layer over a substrate;
- forming a first etch stop over the first insulation layer, the first etch stop layer having an upper surface;
- forming a plurality of contact holes by etching the first insulation layer and the first etch stop layer;
- forming a plurality of contact plugs on the plurality of contact holes, each contact plug having an upper portion that extends above the upper surface of the first etch stop layer;
- forming a second etch stop layer over the contact plugs and the first etch stop layer, the second etch stop layer being substantially non-planar;
- forming a capacitor insulation layer over the second etch stop layer;
- forming a plurality of openings by etching the second etch stop layer and the capacitor insulation layer to expose the contact plugs;
- sequentially forming a storage node material and a sacrificial layer;
- etching the storage node material and the sacrificial layer, thereby obtaining isolated storage node material; and
- removing remaining portions of the sacrificial layer and the capacitor insulation layer.

2. The method of claim **1**, wherein the first etch stop layer is formed in a thickness ranging from approximately 300 Å to approximately 500 Å.

3. The method of claim **1**, wherein each of the upper portions of the contact plugs extends above the upper surface of the first etch stop layer from approximately 300 Å to approximately 500 Å.

4. The method of claim **1**, wherein the step of forming the plurality of contact holes includes:

- forming a second insulation layer on the first etch stop layer;
- etching the first insulation layer, the first etch stop layer and the second insulation layer, thereby obtaining the plurality of contact holes; and
- removing the second insulation layer.

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5. The method of claim **4**, wherein the first insulation layer, the first etch stop layer and the second insulation layer are etched by using high density plasmas having a ratio of approximately 2 to 3 of C_xHF_x to approximately 1 of C_xF_x .

6. The method of claim **5**, wherein the first insulation layer, the first etch stop layer and the second insulation layer are etched by using one of plasma etchers selected from a group of an in-plane switching (IPS) etcher, an inductively coupled plasma (ICP) etcher, a transformer coupled plasma (TCP) etcher and an electron cyclotron resonance (ECR) etcher.

7. The method of claim **1**, wherein the step of forming the plurality of contact plugs includes the steps:

- forming a polysilicon layer on the contact holes; and
- etching the polysilicon layer through performing one of an etch-back process and a chemical mechanical polishing (CMP) process.

8. The method of claim **7**, wherein the etch-back process is performed by using hydrogen bromide (HBr) and chlorine (Cl_2) in combination under a state of providing a source voltage equal to or greater than approximately 300 W and a bias voltage equal to or less than approximately 100 W at a pressure equal to or less than approximately 10 mT by using a typical transformer coupled plasma (TCP) type plasma source.

9. The method of claim **1**, further including the step of forming a dielectric layer and a plate node material on the substrate.

10. The method of claim **1**, wherein the contact holes and the contact plugs are storage node contact holes and storage node contact plugs, respectively.

11. A method for fabricating a capacitor in a semiconductor memory device, the method comprising:

- forming a first insulation layer over a substrate;
- forming a first etch stop over the first insulation layer, the first etch stop layer having an upper surface;
- forming a contact hole by etching the first insulation layer and the first etch stop layer; and
- forming a contact plug within the plurality of contact hole, the contact plug having an upper portion that extends above the upper surface of the first etch stop layer; the upper portion of the contact plug and the upper surface of the first etch stop layer defining a non-uniform surface; and

forming a storage node structure over the contact plug.

12. The method of claim **11**, further comprising: forming a dielectric layer over the over the contact plugs and the first etch stop layer, the second etch stop layer being substantially non-planar.

13. The method of claim **12**, wherein the dielectric layer is a second etch stop layer.

14. The method of claim **13**, further comprising:

- forming a capacitor insulation layer over the second etch stop layer;
- forming a plurality of openings by etching the second etch stop layer and the capacitor insulation layer to expose the contact plugs;
- forming a sacrificial layer over the storage node structure;
- etching the storage node material and the sacrificial layer to obtain an isolated storage node structure; and
- removing remaining portions of the sacrificial layer and the capacitor insulation layer.

15. A method for fabricating a capacitor in a semiconductor memory device, comprising the steps of: sequentially forming a first insulation layer and a first etch stop layer on a substrate;

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forming a plurality of contact holes by etching the first insulation layer and the first etch stop layer;
forming a plurality of contact plugs on the plurality of contact holes such that the contact plugs are more projected than the first etch stop layer; 5
sequentially forming a second etch stop layer and a capacitor insulation layer;
forming a plurality of openings by etching the second etch stop layer and the capacitor insulation layer to expose the contact plugs; 10
sequentially forming a storage node material and a sacrificial layer;
etching the storage node material and the sacrificial layer, thereby obtaining isolated storage node material; and
removing remaining portions of the sacrificial layer and 15
the capacitor insulation layer,

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wherein the step of forming the plurality of contact plugs includes the steps:
forming a polysilicon layer on the contact holes; and
etching the polysilicon layer through performing one of an etch-back process and a chemical mechanical polishing (CMP) process; and
wherein the etch-back process is performed by using hydrogen bromide (HBr) and chlorine (Cl₂) in combination under a state of providing a source voltage equal to or greater than approximately 300 W and a bias voltage equal to or less than approximately 100 W at a pressure equal to or less than approximately 10 mT by using a typical transformer coupled plasma (TCP) type plasma source.

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